

**AMENDMENTS TO THE CLAIMS**

The following listing of claims replaces all prior versions of claims in the application.

1. (Original): A polishing pad comprising a fiber including organic fiber and a matrix resin holding the fiber, wherein at least the organic fiber is exposed on the work material-side surface thereof.

2. (Original): A polishing pad comprising a fiber including organic fiber and a matrix resin holding the fiber, wherein at least the organic fiber is exposed on the work material-side surface after dressing treatment.

3. (Original): The polishing pad according to claim 1 or 2, wherein the matrix resin contains at least one thermoplastic resin.

4. (Currently amended): The Polishing pad according to ~~any one of Claims 1 to 3~~ claim 1 or 2, wherein the matrix resin is a semicrystalline thermoplastic resin.

5. (Currently amended): The polishing pad according to ~~any one of claims 1 to 4~~ claim 1 or 2, wherein an elastomer is dispersed in the matrix resin.

6. (Original): The polishing pad according to claim 5, wherein the elastomer has a glass transition point of 0°C or less.

7. (Currently amended): The polishing pad according to ~~any one of Claims 1 to 6~~ claim 1 or 2, wherein the fiber is an aromatic polyamide.

8. (Currently amended): The polishing pad according to ~~any one of Claims 1 to 7~~ claim 1 or 2, wherein the polishing pad contains an inorganic fiber in an amount of 1 to 50 wt %.

9. (Currently amended): The polishing pad according to ~~any one of claims 1 to 8~~ claim 1 or 2, wherein the organic fiber has a diameter of 1 mm or less.

10. (Currently amended): The polishing pad according to ~~any one of claims 1 to 9~~ claim 1 or 2, wherein the organic fiber has a length of 1 cm or less.

11. (Currently amended): The polishing pad according to ~~any one of Claims 1 to 10~~ claim 1 or 2, wherein polishing particles are held by the organic fiber exposed on the work material-side surface.

12. (Currently amended): The polishing pad according to ~~any one of Claims 1 to 11~~ claim 1 or 2, wherein the maximum length of the exposed organic fiber is 0.1 mm or less.

13. (Original): The polishing pad according to Claim 12, wherein the exposed organic fiber is a polyester fiber.

14. (Currently amended): The polishing pad according to Claim 12 [[or 13]], wherein a chopped polyester fiber is dispersed in the matrix resin.

15. (Currently amended): The polishing pad according to Claim 12 [[or 13]], wherein a polyester nonwoven fabric is laminated in the matrix resin.

16. (Currently amended): The polishing pad according to ~~any one of Claims 1, 2 to 4, 7 and 9 to 11~~ claim 1 or 2 that is useful for optical detection of the polishing end point during polishing of the work material surface, wherein the polishing pad contains a substantially non-foam matrix resin containing an organic fiber in an amount of 1 to 20 wt %, has the functions of transporting and retaining polishing slurry particles, and allows transmission of a light having a wavelength in the range of 190 to 3,500 nm.

17. (Currently amended): The polishing pad according to ~~any one of Claims 1, 2 to 4, 7, and 9 to 11~~ claim 1 or 2 that is useful for optical detection of the polishing end point during polishing of the work material surface, wherein the polishing pad contains a region transmitting a light having a wavelength in the range of 190 to 3,500 nm that is made of a substantially non-foam matrix resin containing an organic fiber in an amount of 1 to 20 wt % and has the functions of transporting and retaining polishing slurry particles.

18. (Currently amended): The polishing pad according to Claim 16 [[or 17]], wherein the organic fiber is an aramide fiber

19. (Original): A method for producing a polishing pad for use as attached to a polishing table for flattening a work material's polishing plane, comprising a step of obtaining a mixture of

a fiber including organic fiber and a matrix composition containing a thermoplastic resin by blending, a step of palletizing or tabletizing the mixture, and a step of molding the pellet or tablet into a plate or a sheet shape by extrusion or injection molding.

20. (Original): A method for producing a polishing pad for use as attached to a polishing table for flattening a work material's polishing plane, comprising a step of impregnating a fibrous base material containing organic fiber with a matrix resin composition to form a fibrous resin-impregnated sheet-shaped base material. and a step of laminating fibrous sheet-shaped base materials including the fibrous resin-impregnated sheet-shaped base material and molding the laminate with heating and pressure.

21. (Original): The method for producing a polishing pad according to claim 19 or 20, further including a step of exposing the fiber on the surface.

22. (Currently amended): A polishing method for polishing a work material's polishing plane, comprising polishing a work material. pressing the polishing plane of the work material to the organic fiber-exposed face of the polishing pad according to ~~any one of Claims 1 to 18~~ claim 1 or 2, and sliding the work material and the pad relatively while supplying a polishing slurry between the work material's polishing plane and the polishing pad.

23. (Original): The polishing method for polishing a work material's polishing plane according to Claim 22, wherein the work material polishing plane is a laminate of a conductor layer

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as well as a copper layer formed on an insulation layer having a dielectric constant of 2.7 or less on which wiring and trenches are found.

24. (Currently amended): A polishing method for detecting the polishing end point optically by using the polishing pad according to ~~any one of claims 16 to 18~~ claim 16.